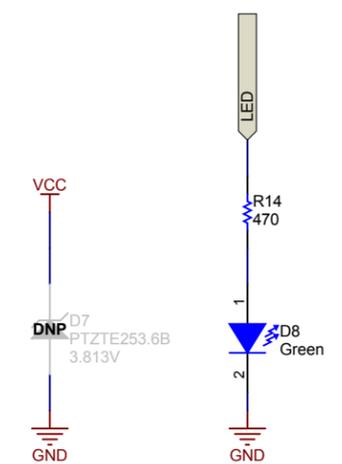
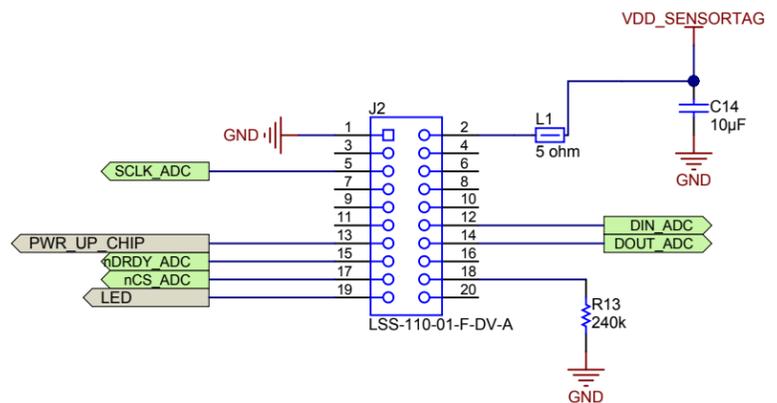
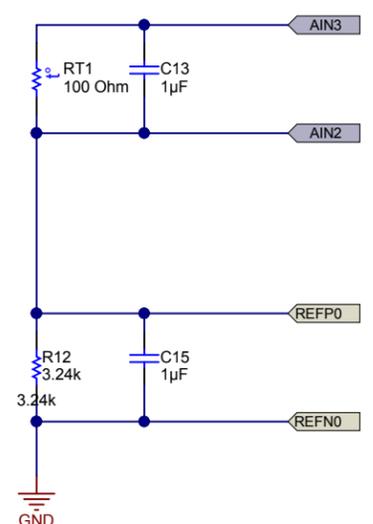
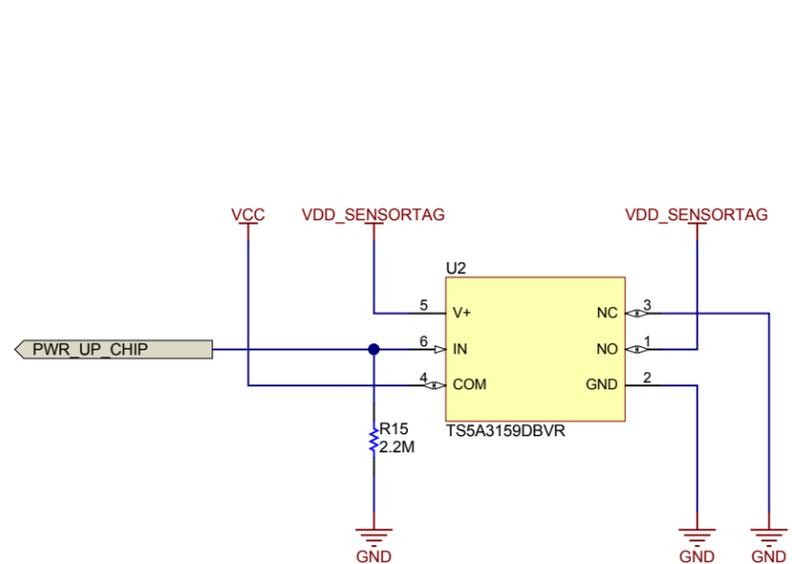
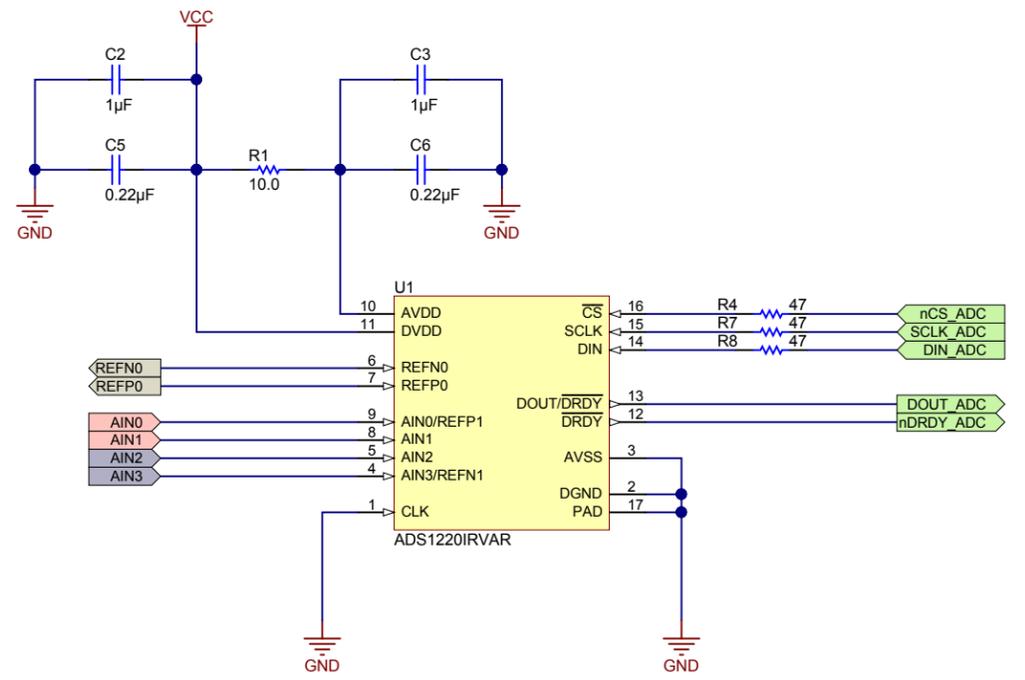
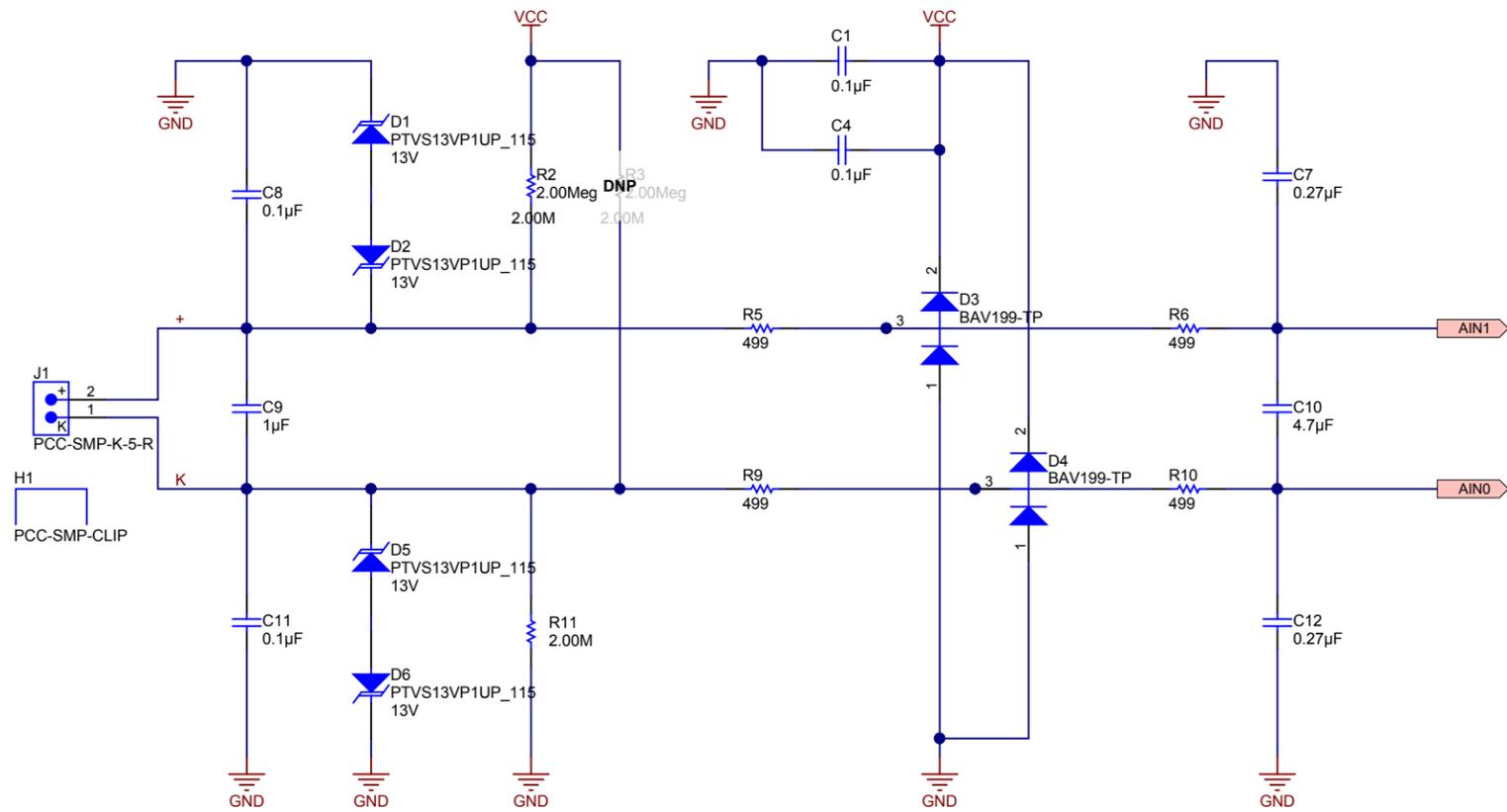


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TID #: TIDA-00650	Project Title: Wireless TC Sensor	Sheet Title: Block Diagram	
Number: TIDA-00650	Rev: E1	Assembly Variant: 001	Sheet: 1 of 3
SVN Rev: Version control disabled	File: TIDA-00650_CoverSheet_SchDoc	Size: B	
Drawn By: AW	Engineer: AW	Contact: http://www.ti.com/support	



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Orderable: N/A	Designed for: Public Release	Mod. Date: 9/16/2015
TID #: TIDA-00650	Project Title: Wireless TC Sensor	
Number: TIDA-00650	Rev: E1	Sheet Title: Thermocouple ADC circuitry
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By: AW	File: TIDA-00650_ADC.SchDoc	Size: B
Engineer: AW	Contact: http://www.ti.com/support	© Texas Instruments 2015



DNP FID1 DNP FID2 DNP FID3

PCB Number: TIDA-00650
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

LBL1
DNP
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

Label Table	
Variant	Label Text
001	TIDA-00650
002	ISFA-EVM-00650

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Orderable: N/A	Designed for: Public Release	Mod. Date: 9/16/2015	
TID #: TIDA-00650	Project Title: Wireless TC Sensor	Sheet: 3 of 3	
Number: TIDA-00650	Rev: E1	Sheet Title: Hardware	http://www.ti.com
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B	
Drawn By: AW	File: TIDA-00650_EVM_Hardware.SchDoc	Contact: http://www.ti.com/support	
Engineer: AW			© Texas Instruments 2015

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